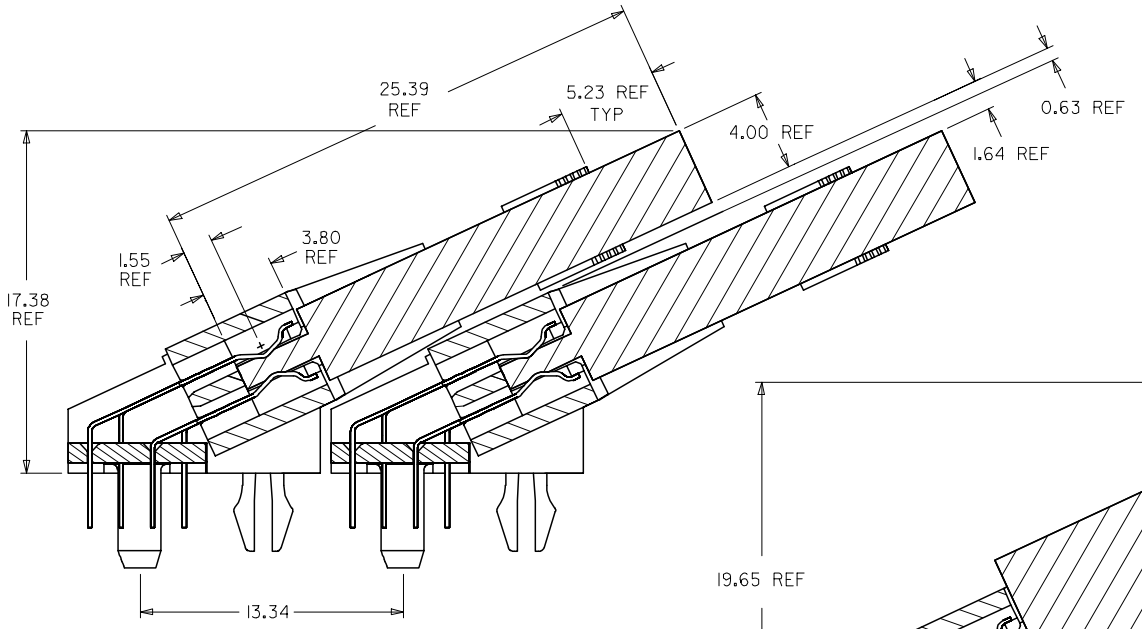


- NOTES:**
- MATERIALS:** HOUSING, BASEPLATE AND LATCH - HIGH TEMPERATURE THERMOPLASTIC, UL 94-V0
TERMINAL AND FORKLOCK - COPPER ALLOY
 - FINISHES:** CONTACT AREA: SEE TABLE ON SHEET 4
SOLDER TAILS: 2.54µm/100µ" MIN. TIN/LEAD OR TIN OVER 1.27µm/50µ" MIN. NICKEL
 - PRODUCT SPECIFICATIONS:** PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
 - DATE CODE** SHALL BE MARKED LEGIBLY AS SHOWN: XX XX YEAR WEEK
 - PART NUMBER** SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX REFER TO TABLE

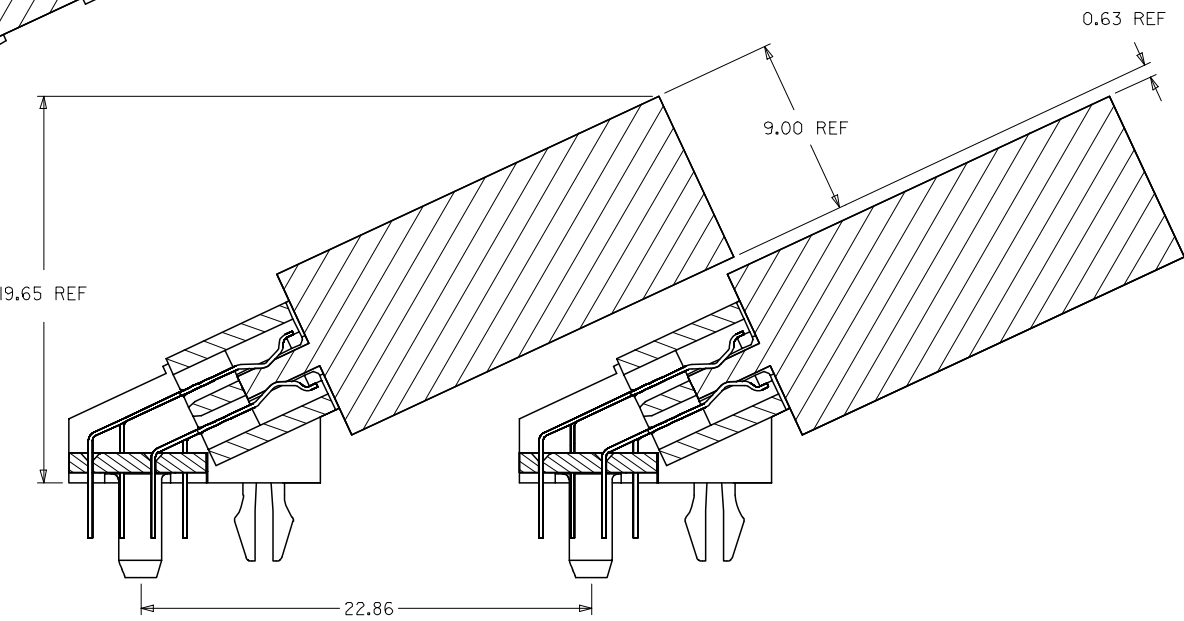
ADD NEW PART NO EC NO: S2005-0439 2004/12/30 DRAWN: SHLENI CHKD: RAMESH APPR: GGLEE 2004/12/30	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	TITLE		SALES DRAWING		
		4 PLACES ± --- ± ---		DRAWN BY LPL IM		DATE 2000/01/10		DDR DIMM, 1.27MM PITCH		
		3 PLACES ± --- ± ---		CHECKED BY DSOH		DATE 2000/02/02		184 CKTS, 25 DEG.		
2 PLACES ± 0.25 ± ---		APPROVED BY SKTOH		DATE 2000/02/02		molex MOLEX INCORPORATED		DOCUMENT NO. SD-87623-001		
1 PLACE ± --- ± ---		MATERIAL NO.		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 1 OF 4		
ANGULAR ± 5 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						

10 9 8 7 6 5 4 3 2 1

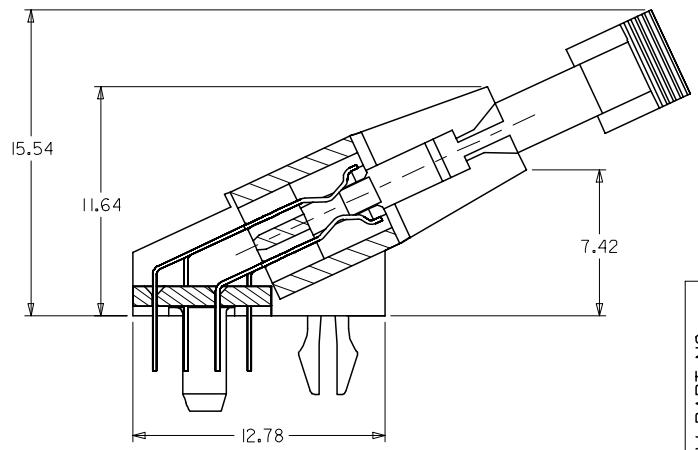
F
E
D
C
B
A



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00 mm THICK
MODULE (TYPICAL TSOP PACKAGING)



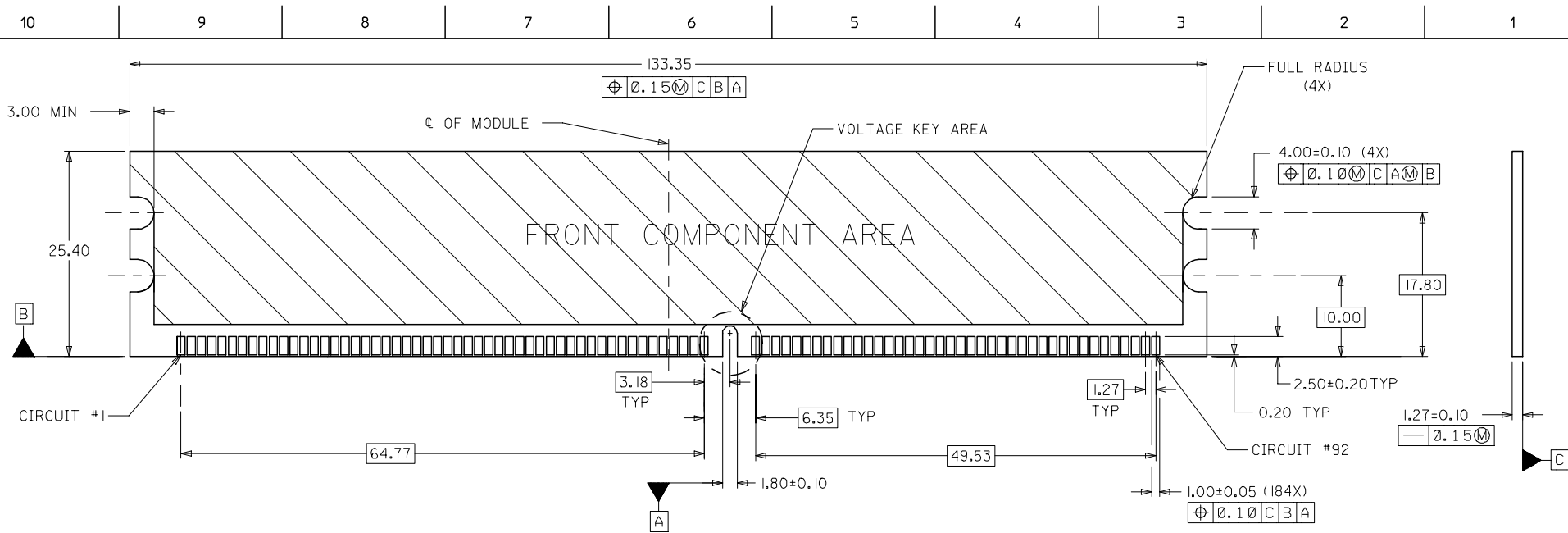
MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 9.00 mm THICK
MODULE (TYPICAL SOJ PACKAGING)



SECTION A-A

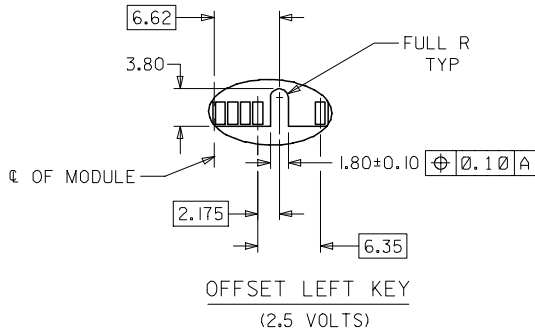
ADD NEW PART NO EC NO: S2005-0439 2004/12/30 DRAWN: SHLENI 2004/12/30 CHKD: RAMESH 2004/12/30 APPR: GGLEE 2004/12/30	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.			
		4 PLACES	± ---	± ---	CHECKED BY DSOH	DATE 2000/02/02				
		3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2000/02/02	MOLEX INCORPORATED			
2 PLACES	± 0.25	± ---	MATERIAL NO.		DOCUMENT NO. SD-87623-001	SHEET NO. 2 OF 4				
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR ± 5 °		SEE TABLE								

9 8 7 6 5 4 3 2 1



RECOMMENDED MODULE LAYOUT
 (PER JEDEC STANDARD MO-206, 184 CKT.)
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ± 0.13

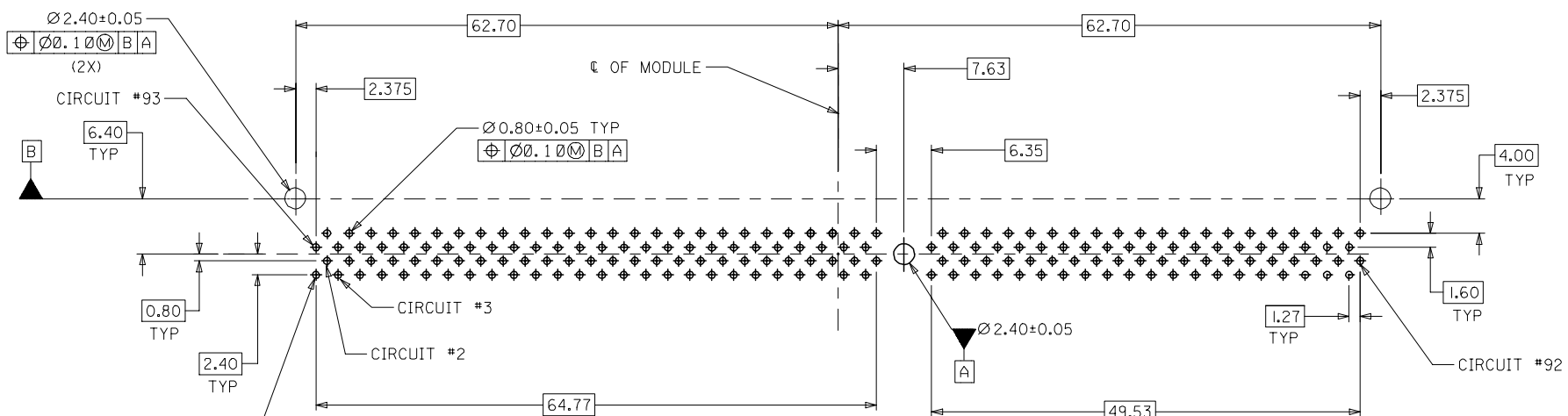
VOLTAGE KEY AREA



ADD NEW PART NO EC NO: S2005-0439 DRAWN: SHLENI 2004/12/30 CHKD: RAMESH 2004/12/30 APPR: GGLEE 2004/12/30	QUALITY SYMBOLS = 0 = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES \pm --- \pm ---	mm INCH	DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.			
		3 PLACES \pm --- \pm ---		CHECKED BY DSOH	DATE 2000/02/02	MOLEX INCORPORATED			
		2 PLACES ± 0.25 \pm ---		APPROVED BY SKTOH	DATE 2000/02/02	MATERIAL NO. SKTOH	DOCUMENT NO. SD-87623-001	SHEET NO. 3 OF 4	
1 PLACE \pm --- \pm ---		ANGULAR $\pm 5^\circ$		SIZE SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

PLATING OPTION	ASSEMBLY PART NUMBER	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH Q±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
TIN/LEAD	87623-0001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
	87623-0011			3.18	4.83	3.94		
	87623-0012			3.18	3.18	3.18		
	87623-0013			3.81	4.83	4.42	2.84	
	87623-0101			2.79	3.18	3.18	1.57	
	87623-0111			3.18	4.83	3.94		
	87623-0113			3.81	4.83	4.42		
87623-0115	3.18	3.18	3.18	1.57				
TIN	87623-2001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
	87623-2011			3.18	4.83	3.94		
	87623-2012			3.18	3.18	3.18		
	87623-2013			3.81	4.83	4.42	2.84	
	87623-2101			2.79	3.18	3.18	1.57	
	87623-2111			3.18	4.83	3.94		
	87623-2113			3.81	4.83	4.42		
	87623-2115			3.18	3.18	3.18	1.57	



RECOMMENDED
P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)

ADD NEW PART NO EC NO: S2005-0439 DRAWN: SHLENI 2004/12/30 CHKD: RAMESH 2004/12/30 APPR: GGLEE 2004/12/30 REV B1	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	mm INCH	DRAWN BY LPL IM	DATE 2000/01/10	TITLE SALES DRAWING DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	APPROVED BY SKTOH	DATE 2000/02/02	MOLEX INCORPORATED
				MATERIAL NO.	DOCUMENT NO. SD-87623-001	SHEET NO. 4 OF 4

9 8 7 6 5 4 3 2 1